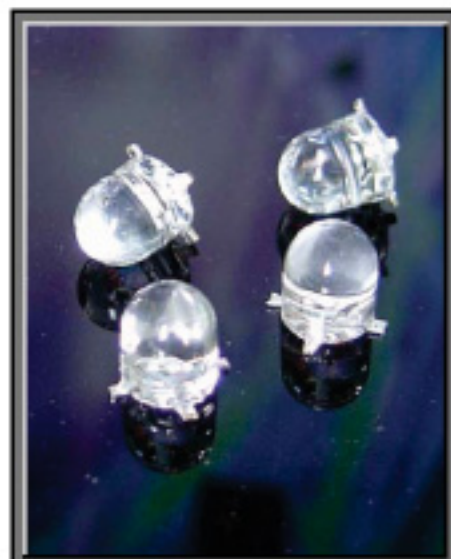


◎ MOLDING TYPE SMD LED LAMPS

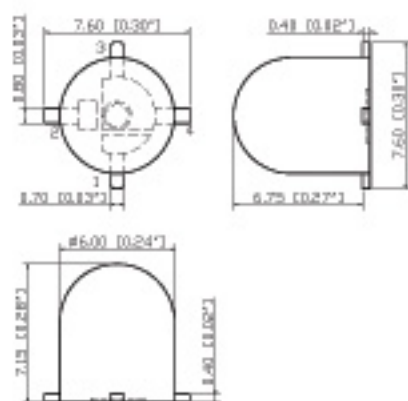
灌注型表面粘著發光二極體指示燈

GH-5168-L6 Multi-Color Series Electro-Optical Characteristics:

Code for parts GH-XXXXX	Lighting Color	Material	V _F (V)		λ (nm)			Chip I _V (mcd)	Internal Circuit
			Typ	Max	λ _D	λ _P	Δλ		
MPEKM8T4-L6E	Red	AlGaInP	2.00	2.50	630	640	20	80	
	Green	AlGaInP	2.00	2.50	574	575	20	25	
MPENM8T4-L6E	Orange	AlGaInP	2.00	2.50	624	635	20	80	
	Green	AlGaInP	2.00	2.50	574	575	20	25	
MPEMM8T4-L6H	Green	GaInN	3.30	3.80	525	520	30	160	
	Blue	GaInN	3.50	4.00	465	460	30	40	
MPELM8T4-L6E	Yellow	AlGaInP	2.00	2.50	590	595	20	80	
	Blue	GaInN	3.50	4.00	465	460	30	40	



◎ Package Outline Drawing:

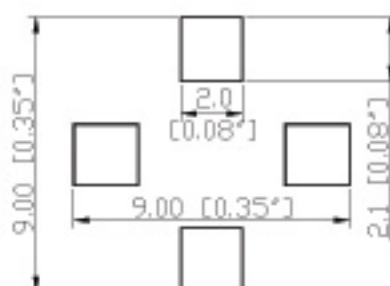


- NOTES: 1. All dimensions are in millimeters (inches);
2. Tolerances are $\pm 0.2\text{mm}$ (0.008inch) unless otherwise noted;
3. Resin color: white diff.

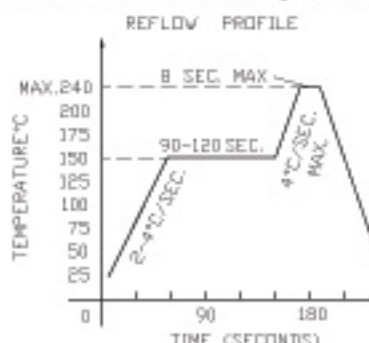
★ Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^\circ\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

★ Recommended Soldering Pattern For Reflow Soldering



★ Recommended Reflow Soldering Profile.



◎ Absolute Maximum Ratings:

Series	I _F (mA)	*I _{FP} (mA)	V _R (V)	T _{OP} ($^\circ\text{C}$)	T _{ST} ($^\circ\text{C}$)
GH-5168-L6 Multi-Color Series	30	120	5	-40~+80	-40~+85

★Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width